

Product data sheet

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Applications

- Cellular phones
- Portable devices
- Digital cameras
- Power supplies

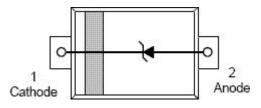
Features

- Small Body Outline Dimensions
- Low Body Height
- Stand-off Voltage: 2.5 V 12 V
- Peak Power up to 200 Watts @ 8 x 20 _s Pulse
- Low Leakage
- Response Time is Typically < 1 ns
- ESD Rating of Class 3 (> 16 kV) per Human Body Model
- IEC61000-4-2 Level 4 ESD Protection
- IEC61000–4–4 Level 4 EFT Protection
- We declare that the material of product compliance with RoHS requirements.
- S- Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

Absolute Ratings (T_{amb}=25°C)

Symbol	Parameter		Value	Units
P _{PP}	Peak Pulse Power (t _p = 8/20µs)	200	W	
ΤL	Maximum lead temperature for soldering du	Maximum lead temperature for soldering during 10s		°C
T _{stg}	Storage Temperature Range		-55 to +150	°C
T _{op}	Operating Temperature Range		-40 to +125	°C
Tj	Maximum junction temperature		150	°C
	IEC61000-4-2 (ESD)	air discharge contact discharge	土15 土8	KV
	IEC61000-4-4 (EFT)		40	А
	ESD Voltage	Per Human Body Model	16	KV





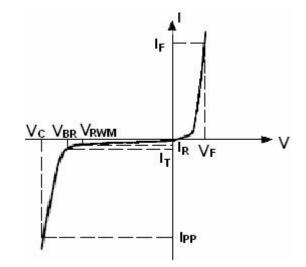




Semiconductor

Electrical Parameter

Symbol	Parameter	
I _{PP}	Maximum Reverse Peak Pulse Current	
Vc	Clamping Voltage @ IPP	
V _{RWM}	Working Peak Reverse Voltage	
I _R	Maximum Reverse Leakage Current @ V _{RWM}	
Ι _Τ	Test Current	
V _{BR}	Breakdown Voltage @ I⊤	
IF	Forward Current	
VF	Forward Voltage @ I _F	



Electrical Characteristics Ratings at 25°C ambient temperature unless otherwise specified.VF = 0.9V at IF = 10mA

Device	Device	V _{RWM} (V)	I _R (uA) @ V _{RWM}	V _{BR} (V)@ I _T (Note 1)	Ιτ	Vc (V) @ I _{PP} =5 A*	V _C (V) @ Max I _{PP} *	І _{РР} (А)*	Р _{РК} (W)*	C (pF)
	Marking	Max	Мах	Min	mA	Тур	Max	Max	Мах	Тур
ESD5Z2V5-MS	ZD	2.5	6.0	4.0	1.0	6.5	10.9	11.0	120	145
ESD5Z3V3-MS	ZE	3.3	1.0	5.0	1.0	8.4	14.1	11.2	158	105
ESD5Z5V0-MS	ZF	5.0	1.0	6.2	1.0	11.6	18.6	9.4	174	80
ESD5Z6V0-MS	ZG	6.0	1.0	6.8	1.0	12.4	20.5	8.8	181	70
ESD5Z7V0-MS	ZH	7.0	1.0	7.5	1.0	13.5	22.7	8.8	200	65
ESD5Z12V-MS	ZM	12	1.0	13.5	1.0	17	25	9.6	240	55

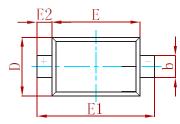
*Surge current waveform per Figure 1.

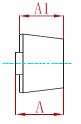
1. V_{BR} is measured with a pluse test current I_T at an ambient temperature of $25\,^\circ\! {\rm C}$.

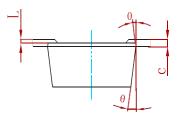




PACKAGE MECHANICAL DATA

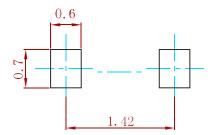






Symbol	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
A	0.510	0.770	0.020	0.031	
A1	0.500	0.700	0.020	0.028	
b	0.250	0.350	0.010	0.014	
С	0.080	0.150	0.003	0.006	
D	0.750	0.850	0.030	0.033	
E	1.100	1.300	0.043	0.051	
E1	1.500	1.700	0.059	0.067	
E2	0.200 REF		0.008 REF		
L	0.010	0.070	0.001	0.003	
0	7° REF		7° REF		

Suggested Pad Layout



Note:

1.Controlling dimension:in millimeters.

2.General tolerance:± 0.05mm.

3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
ESD5ZXXX-MS	SOD-523	3000





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